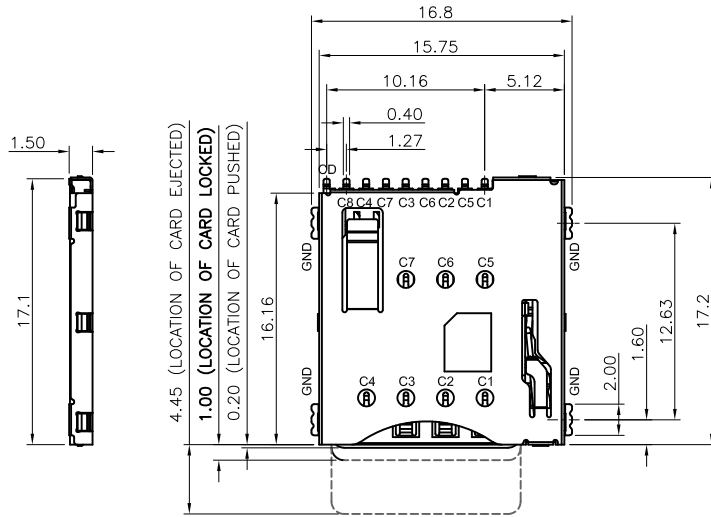
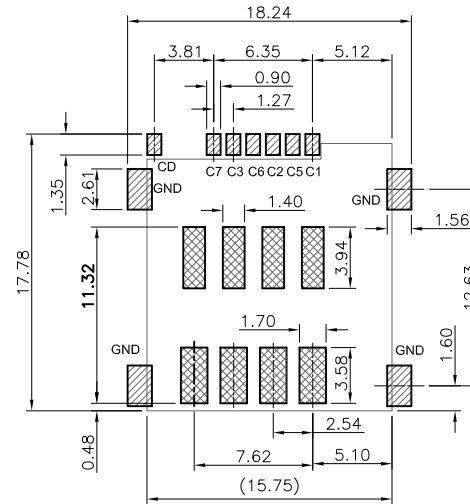


MICRO SIM CARD



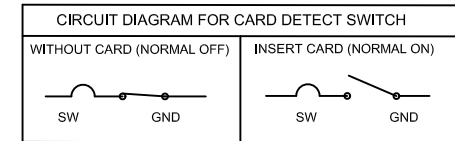
RECOMMENDED P.C.B LAYOUT
ALL TOLERANCE $\pm 0.05\text{mm}$

-  SOLDER AREA
-  NONE CIRCUIT DIAGRAM AREA

SPECIFICATION:

1. Current Rating: 0.5A
2. Voltage Rating: 50V DC
3. Contact Resistance: 100m Ω Max.
4. Insulator Resistance: 1000M Ω Min.
5. Withstanding Voltage: 500V AC
6. Durability: 5,000 Cycles
7. Operating Temperature : -40°C ~ +70°C

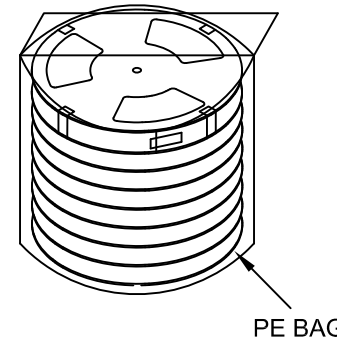
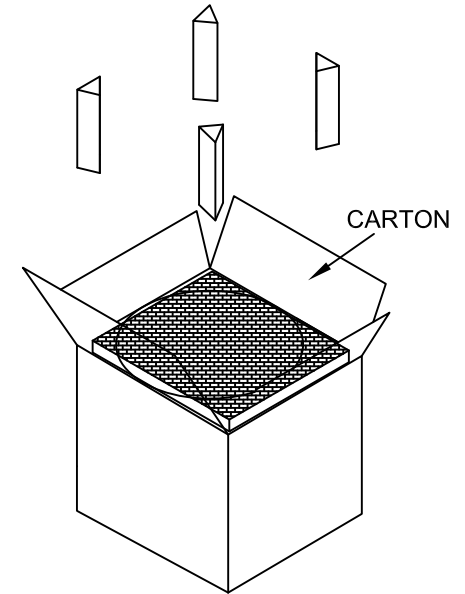
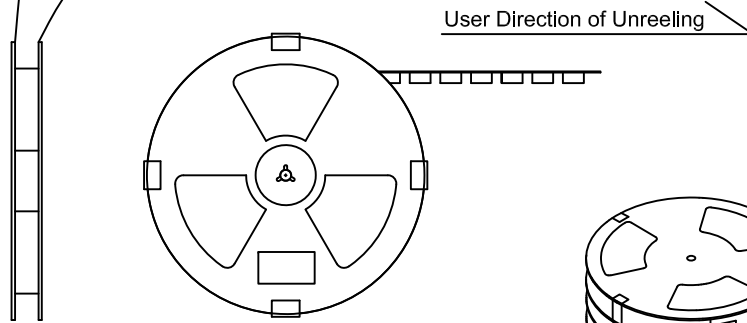
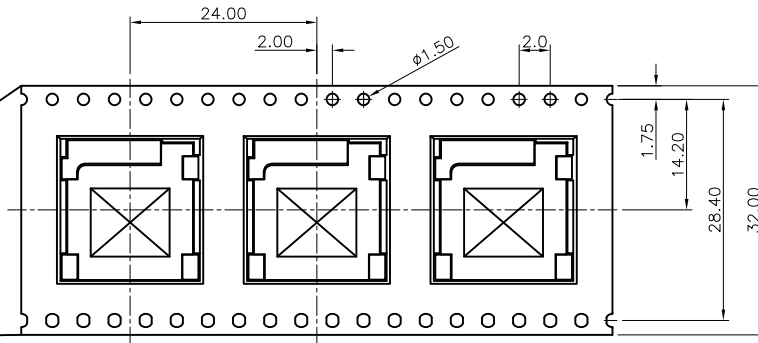
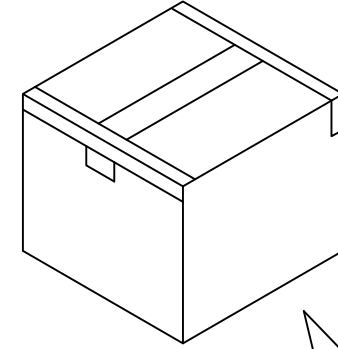
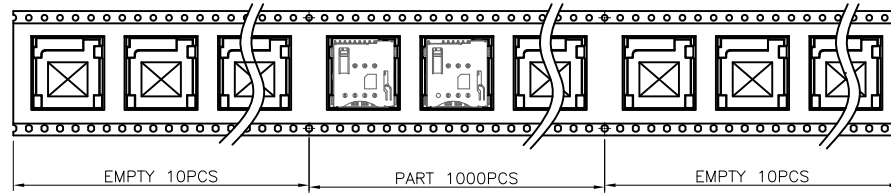
PIN NO.	DESCRIPTION
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O



6.	CAM PIN	Stainless Steel
5.	COLL SPRING	SWP.
4.	HEART CAM	Hi-Temp Thermoplastic UL94v-0, Black
3.	SHELL	Stainless Steel , Ni Plated
2.	CONTACT	Copper Alloy , Gold Plating on Contact Area
1.	HOUSING	Hi-Temp Thermoplastic UL94v-0, Black

NO.	PART NAME	DESCRIPTION
6.	CAM PIN	Stainless Steel
5.	COLL SPRING	SWP.
4.	HEART CAM	Hi-Temp Thermoplastic UL94v-0, Black
3.	SHELL	Stainless Steel , Ni Plated
2.	CONTACT	Copper Alloy , Gold Plating on Contact Area
1.	HOUSING	Hi-Temp Thermoplastic UL94v-0, Black
Chunxin Technology		
NAME		
Micro SIM Socket Push Push Type 8Pin w/switch, H=1.5mm		
PRODUCT No. CX1-MSM8201-41		
DRAWING No. CS-MSM005		

1	8	9	10
1	INITIAL RELEASE	JACK WU	2017/09/18
2	NEW FORM	JACK WU	2020/05/04
3			



NOTES

- NUMBER OF CONNECTORS :
1,000 PCS / REEL ; 10,000 PCS / CARTON 10 REELS
- LEAD TAPE LENGTH

NO.	PART NAME		DESCRIPTION	
DIMENSIONS : mm 	TOLERANCES UNLESS OTHERWISE SPECIFIED :		Chunxin Technology NAME	
	X, ± 0.30 X.X, ± 0.20 X.XX, ± 0.10 ANGLES ± 3°			
SCALE	DWN	20170918	Micro SIM Socket Push Push Type 8Pin w/switch, H=1.5mm	
1 : X	JACK WU	20170918		
SHEET	CHK	20170918		
2/2	PETER WANG	20170918		
SIZE	APVD	20170918	PRODUCT No. CX1-MSM8201-41	
A4	SIMON LI	20170918		
CUSTOMER DRAWING			DRAWING No. CS-MSM005	